

Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Fast Switching Speed
- Green Device Available

Applications

- Power Tools.
- Motor Control.
- UPS
- Synchronous Rectification in SMPS

Product Summary

BVDSS	RDSON	ID
100V	2.5mΩ	308A

TO263 Pin Configuration

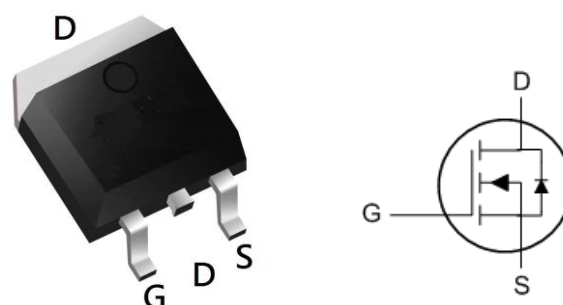


Table1 Absolute Maximum Ratings (Tc=25°C, unless otherwise specified)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ^{1,6}	I _D @T _C =25°C	308	A
Continuous Drain Current ^{1,6}	I _D @T _C =100°C	218	A
Pulsed Drain Current ²	I _{DM}	550	A
Single Pulse Avalanche Energy ³	EAS	2000	mJ
Avalanche Current	I _{AS}	45	A
Total Power Dissipation ⁴	P _D @T _C =25°C	429	W
Storage Temperature Range	T _{STG}	-55 to 175	°C
Operating Junction Temperature Range	T _J	-55 to 175	°C

Table 2. Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction-Ambient ¹	R _{θJA}	---	60	°C/W
Thermal Resistance Junction-Case ¹	R _{θJC}	---	0.35	°C/W

Table 3. Electrical Characteristics (T_J=25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V , I _D =250uA	100	---	---	V
Static Drain-Source On-Resistance ²	R _{DS(ON)}	V _{GS} =10V , I _D =50A	---	2.1	2.5	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	2	---	4	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =80V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =80V , V _{GS} =0V , T _J =100°C	---	---	100	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
Forward Transconductance	g _{fs}	V _{DS} =5V , I _D =20A	---	75	---	S
Total Gate Charge	Q _g	V _{DS} =50V , V _{GS} =10V , I _D =50A	---	206	---	nC
Gate-Source Charge	Q _{gs}		---	67.6	---	
Gate-Drain Charge	Q _{gd}		---	47.7	---	
Turn-On Delay Time	T _{d(on)}	V _{DD} =50V , V _{GS} =10V , R _G =3Ω, I _D =20A	---	47	---	ns
Rise Time	T _r		---	28	---	
Turn-Off Delay Time	T _{d(off)}		---	79	---	
Fall Time	T _f		---	18	---	
Input Capacitance	C _{iss}	V _{DS} =50V , V _{GS} =0V , f=1MHz	---	14420	---	pF
Output Capacitance	C _{oss}		---	1262	---	
Reverse Transfer Capacitance	C _{rss}		---	298	---	
Diode Characteristics						
Continuous Source Current ^{1,5,6}	I _S	V _G =V _D =0V , Force Current	---	---	80	A
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V , I _S =1A , T _J =25°C	---	---	1.1	V
Reverse Recovery Time	t _{rr}	I _F =20A , di/dt=100A/μs , T _J =25°C	---	70	---	nS
Reverse Recovery Charge	Q _{rr}		---	580	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch²FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=50V,V_{GS}=10V,L=0.5mH
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as I_D and I_S , in real applications , should be limited by total power dissipation.
6. Bonding wire limitation current is 120A.

Typical Characteristics

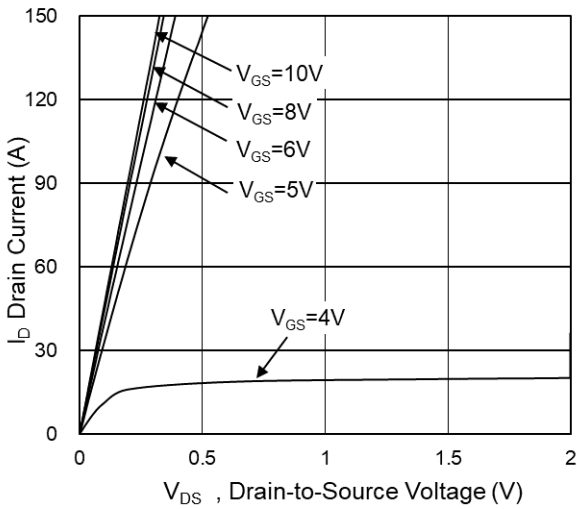


Fig.1 Typical Output Characteristics

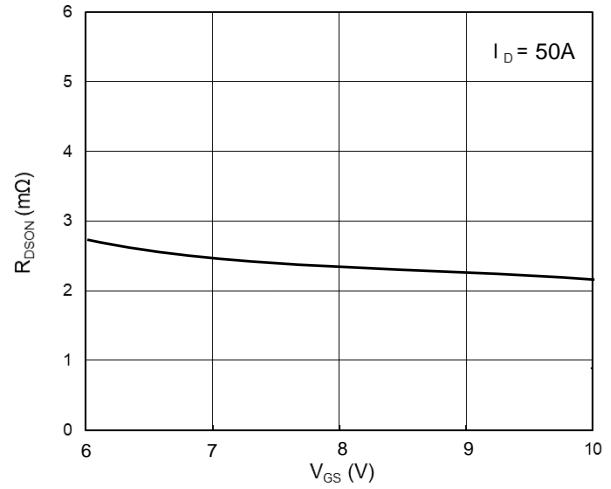


Fig.2 On-Resistance vs G-S Voltage

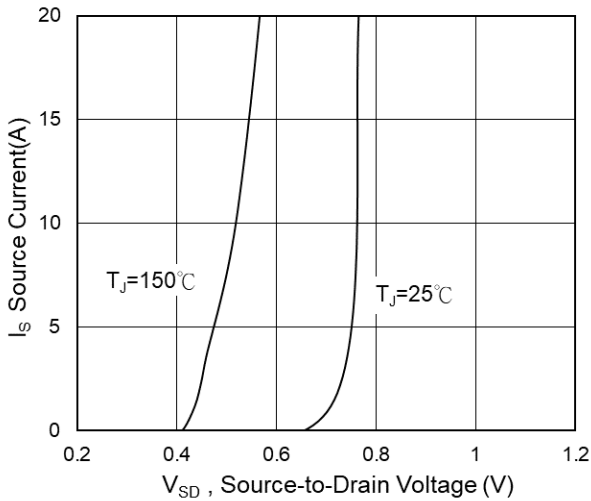


Fig.3 Source-Drain Forward Characteristics

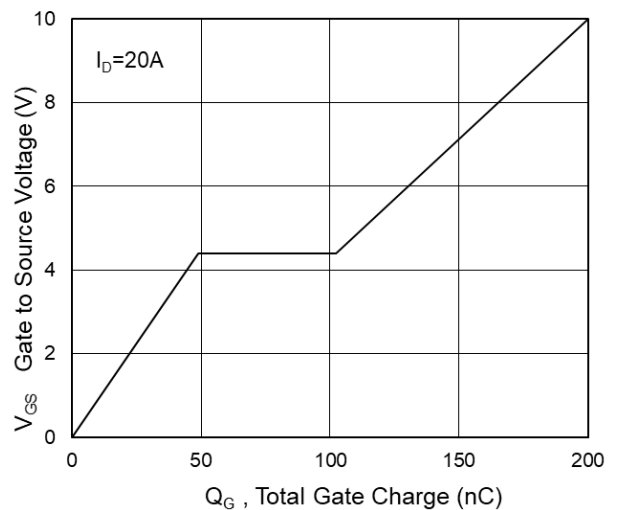


Fig.4 Gate-Charge Characteristics

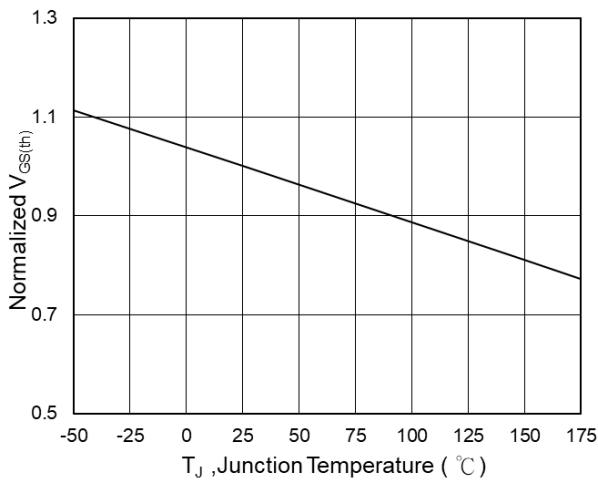


Fig.5 Normalized $V_{GS(th)}$ vs T_J

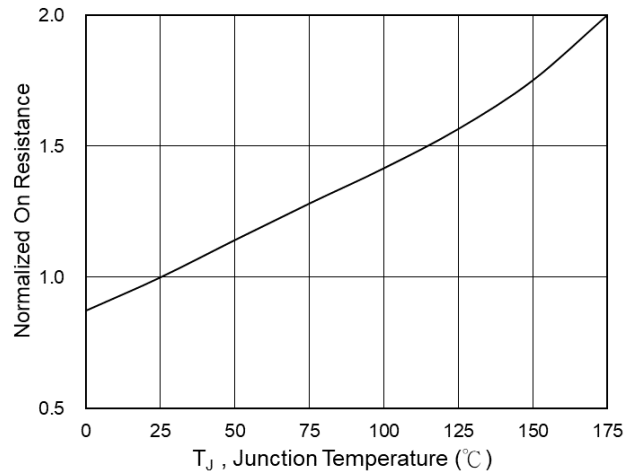


Fig.6 Normalized $R_{DS(on)}$ vs T_J

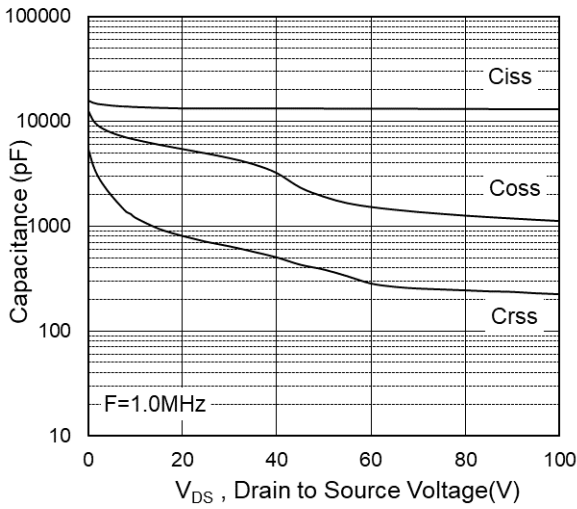


Fig.7 Capacitance

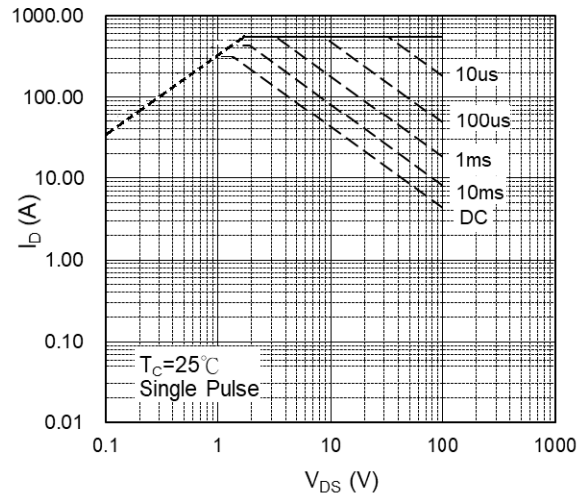


Fig.8 Safe Operating Area

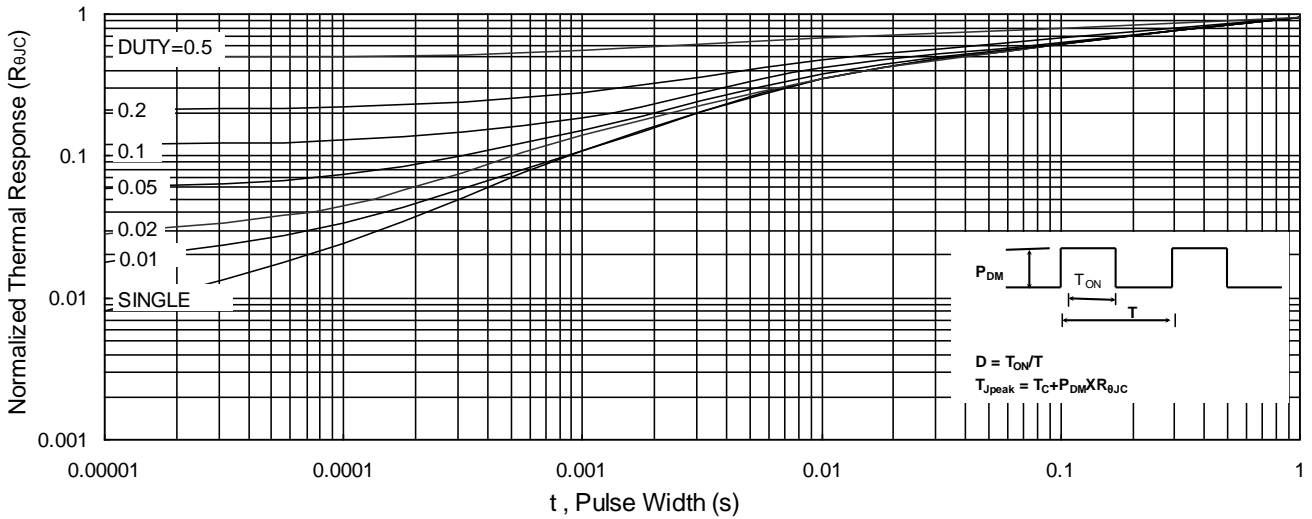


Fig.9 Normalized Maximum Transient Thermal Impedance

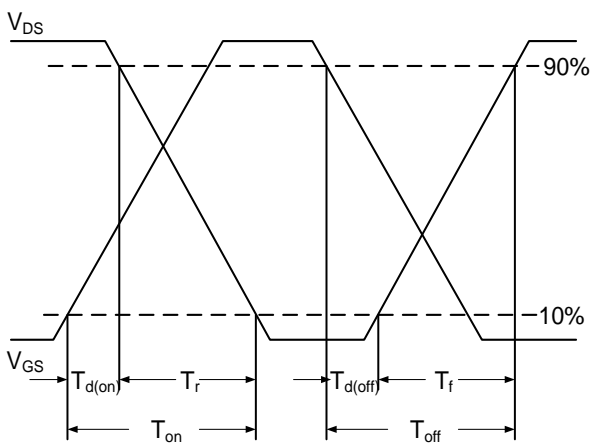


Fig.10 Switching Time Waveform

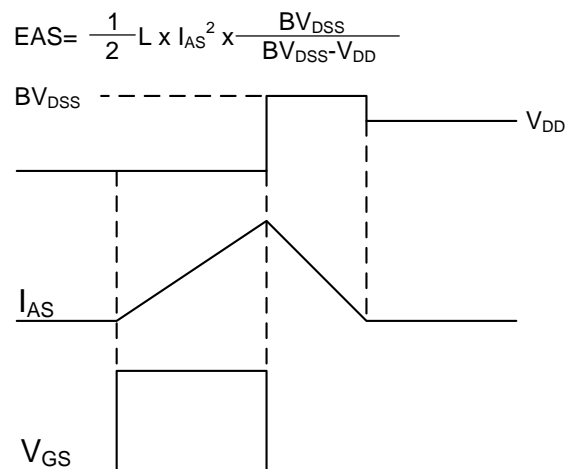
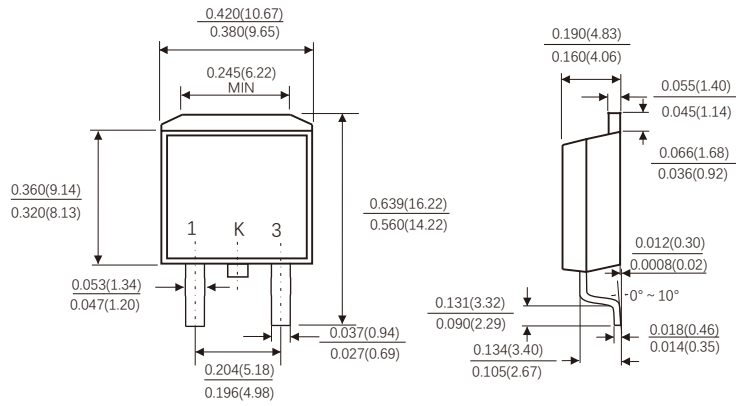


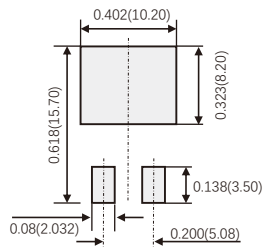
Fig.11 Unclamped Inductive Switching Waveform

TO-263



Suggested Pad Layout

(TO-263)



(设计者可参考推荐值根据焊接工艺要求自行确定适合的焊盘尺寸)
 (Designers can refer to the recommended values according to the manufacturing process requirements to determine the appropriate pad size)

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